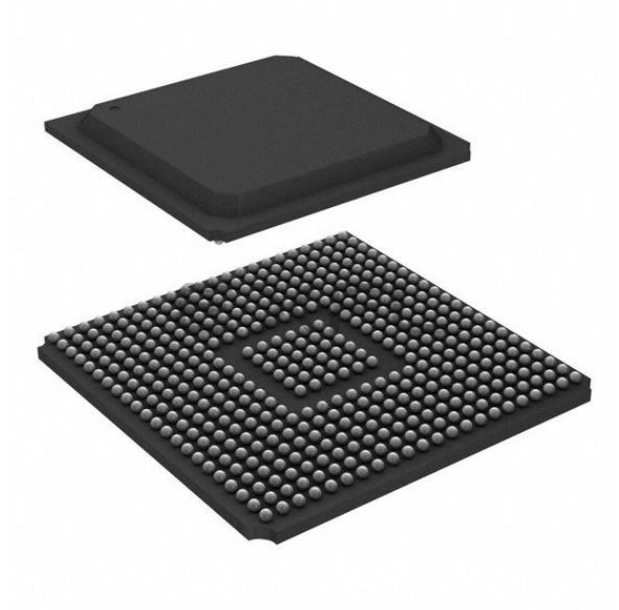

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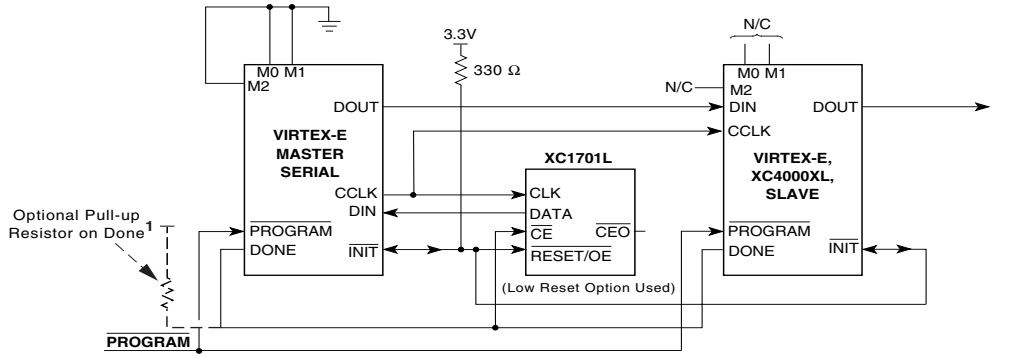
Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1176
Number of Logic Elements/Cells	5292
Total RAM Bits	114688
Number of I/O	284
Number of Gates	306393
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv200e-8fg456c



Note 1: If none of the Virtex FPGAs have been selected to drive DONE, an external pull-up resistor of 330 Ω should be added to the common DONE line. (For Spartan-XL devices, add a 4.7K Ω pull-up resistor.) This pull-up is not needed if the DriveDONE attribute is set. If used, DriveDONE should be selected only for the last device in the configuration chain.

XCVE_ds_013_050103

Figure 13: **Master/Slave Serial Mode Circuit Diagram**

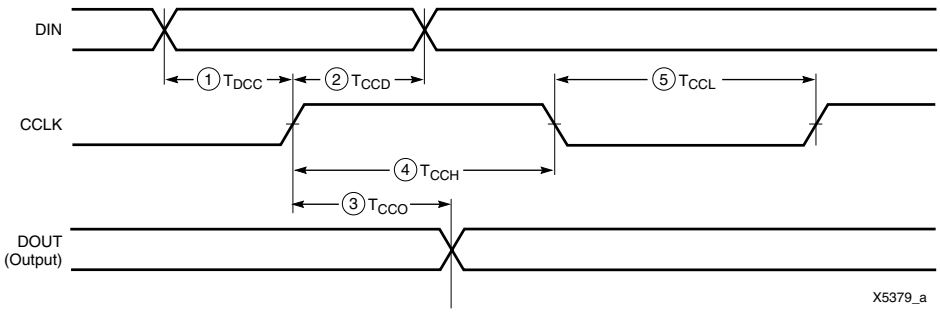


Figure 14: **Slave-Serial Mode Programming Switching Characteristics**

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge. The maximum capacity for a single LOUT/DOUT write is 2^{20}-1 (1,048,575) 32-bit words, or 33,554,4000 bits.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK frequency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

In a full master/slave system (Figure 13), the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM $\overline{\text{RESET}}$ pin is driven by $\overline{\text{INIT}}$, and the $\overline{\text{CE}}$ input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

Because any single DLL can access only two BUFGs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in Figure 30. Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal deskewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal deskewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

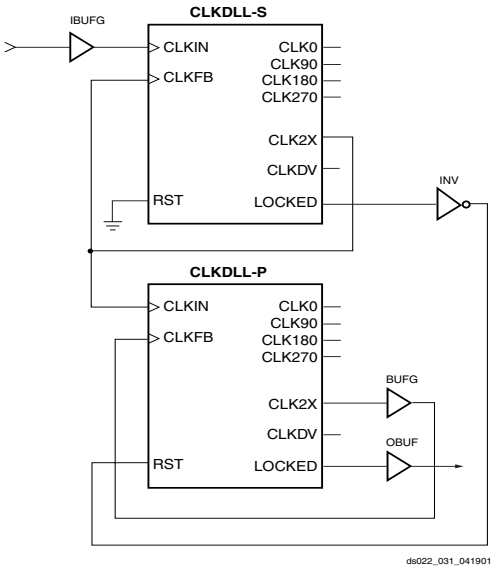


Figure 30: **DLL Generation of 4x Clock in Virtex-E Devices**

The dll_4xe files in the xapp132.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. The block SelectRAM+ memory offers new capabilities allowing the FPGA designer to simplify designs.

Operating Modes

VIrtex-E block SelectRAM+ memory supports two operating modes:

- Read Through
- Write Back

Read Through (one clock edge)

The read address is registered on the read port clock edge and data appears on the output after the RAM access time. Some memories might place the latch/register at the outputs, depending on whether a faster clock-to-out versus set-up time is desired. This is generally considered to be an inferior solution, since it changes the read operation to an asynchronous function with the possibility of missing an address/control line transition during the generation of the read pulse clock.

Write Back (one clock edge)

The write address is registered on the write port clock edge and the data input is written to the memory and mirrored on the output.

Block SelectRAM+ Characteristics

- All inputs are registered with the port clock and have a set-up to clock timing specification.
- All outputs have a read through or write back function depending on the state of the port WE pin. The outputs relative to the port clock are available after the clock-to-out timing specification.
- The block SelectRAMs are true SRAM memories and do not have a combinatorial path from the address to the output. The LUT SelectRAM+ cells in the CLBs are still available with this function.
- The ports are completely independent from each other (*i.e.,* clocking, control, address, read/write function, and data width) without arbitration.
- A write operation requires only one clock edge.
- A read operation requires only one clock edge.

The output ports are latched with a self timed circuit to guarantee a glitch free read. The state of the output port does not change until the port executes another read or write operation.

Library Primitives

Figure 31 and Figure 32 show the two generic library block SelectRAM+ primitives. Table 14 describes all of the available primitives for synthesis and simulation.

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

map –pr b <filename>

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

LOC=A42

LOC=P37

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

SLEW=SLOW

SLEW=FAST

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTL output buffers (OBUF, OBUFT, and IOBUF, the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

DRIVE=2
DRIVE=4
DRIVE=6
DRIVE=8
DRIVE=12 (Default)
DRIVE=16
DRIVE=24

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at **http://www.bourns.com**.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

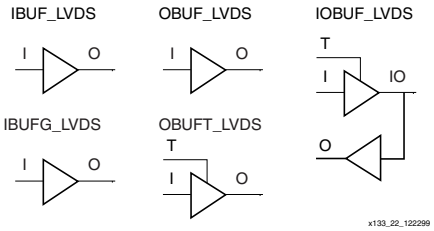


Figure 58: **LVDS elements**

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLKPAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
Pkg	P	N	P	N	P	N	P	N
CS144	A6	C6	A7	B7	M7	M6	K7	N8
PQ240	P213	P215	P210	P209	P89	P87	P92	P93
HQ240	P213	P215	P210	P209	P89	P87	P92	P93
BG352	D14	A15	B14	A13	AF14	AD14	AE13	AC13
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG256	B8	A7	C9	A8	R8	T8	N8	N9
FG456	C11	B11	A11	D11	YII	AA11	W12	U12
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG680	A20	C22	D21	A19	AU22	AT22	AW19	AT21
FG860	C22	A22	B22	D22	AY22	AW21	BA22	AW20
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16
FG1156	E17	C17	D17	J18	AI19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

DC Characteristics Over Recommended Operating Conditions

Symbol	Description		Device	Min	Max	Units
V_{DRINT}	Data Retention V_{CCINT} Voltage (below which configuration data might be lost)		All	1.5		V
V_{DRIO}	Data Retention V_{CCO} Voltage (below which configuration data might be lost)		All	1.2		V
I_{CCINTQ}	Quiescent V_{CCINT} supply current (Note 1)		XCV50E		200	mA
			XCV100E		200	mA
			XCV200E		300	mA
			XCV300E		300	mA
			XCV400E		300	mA
			XCV600E		400	mA
			XCV1000E		500	mA
			XCV1600E		500	mA
			XCV2000E		500	mA
			XCV2600E		500	mA
			XCV3200E		500	mA
I_{CCOQ}	Quiescent V_{CCO} supply current (Note 1)		XCV50E		2	mA
			XCV100E		2	mA
			XCV200E		2	mA
			XCV300E		2	mA
			XCV400E		2	mA
			XCV600E		2	mA
			XCV1000E		2	mA
			XCV1600E		2	mA
			XCV2000E		2	mA
			XCV2600E		2	mA
			XCV3200E		2	mA
I_L	Input or output leakage current		All	–10	+10	µA
C_{IN}	Input capacitance (sample tested)	BGA, PQ, HQ, packages	All		8	pF
I_{RPU}	Pad pull-up (when selected) @ V_{in} = 0 V, V_{CCO} = 3.3 V (sample tested)		All	Note 2	0.25	mA
I_{RPD}	Pad pull-down (when selected) @ V_{in} = 3.6 V (sample tested)			Note 2	0.25	mA

Notes:
1. With no output current loads, no active input pull-up resistors, all I/O pins 3-stated and floating.
2. Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not guarantee valid logic levels when input pins are connected to other circuits.

Block RAM Switching Characteristics

Description	Symbol	Speed Grade(1)				Units
		Min	-8	-7	-6	
Sequential Delays						
Clock CLK to DOUT output	T_{BCKO}	0.63	2.46	3.1	3.5	ns, max
Setup and Hold Times before Clock CLK						
ADDR inputs	T_{BACK}/T_{BCKA}	0.42 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
DIN inputs	T_{BDCK}/T_{BCKD}	0.42 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
EN input	T_{BECK}/T_{BCKE}	0.97 / 0	2.0 / 0	2.2 / 0	2.5 / 0	ns, min
RST input	T_{BRCK}/T_{BCKR}	0.9 / 0	1.8 / 0	2.1 / 0	2.3 / 0	ns, min
WEN input	T_{BWCK}/T_{BCKW}	0.86 / 0	1.7 / 0	2.0 / 0	2.2 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T_{BPWH}	0.6	1.2	1.35	1.5	ns, min
Minimum Pulse Width, Low	T_{BPWL}	0.6	1.2	1.35	1.5	ns, min
CLKA -> CLKB setup time for different ports	T_{BCCS}	1.2	2.4	2.7	3.0	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

TBUF Switching Characteristics

Description	Symbol	Speed Grade				Units
		Min	-8	-7	-6	
Combinatorial Delays						
IN input to OUT output	T_{IO}	0.0	0.0	0.0	0 .0	ns, max
TRI input to OUT output high-impedance	T_{OFF}	0.05	0.092	0.10	0.11	ns, max
TRI input to valid data on OUT output	T_{ON}	0.05	0.092	0.10	0.11	ns, max

JTAG Test Access Port Switching Characteristics

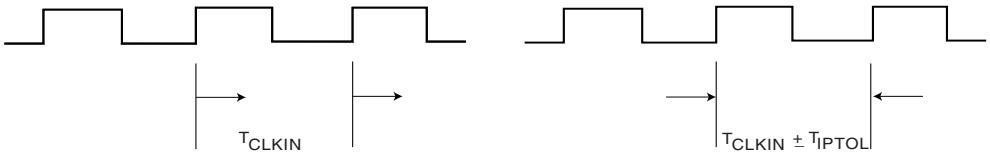
Description	Symbol	Value	Units
TMS and TDI Setup times before TCK	T_{TAPTK}	4.0	ns, min
TMS and TDI Hold times after TCK	T_{TCKTAP}	2.0	ns, min
Output delay from clock TCK to output TDO	T_{TCKTDO}	11.0	ns, max
Maximum TCK clock frequency	F_{TCK}	33	MHz, max

DLL Timing Parameters

All devices are 100 percent functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Description	Symbol	F_{CLKIN}	Speed Grade						Units
			-8		-7		-6		
			Min	Max	Min	Max	Min	Max	
Input Clock Frequency (CLKDLLHF)	FCLKINHF		60	350	60	320	60	275	MHz
Input Clock Frequency (CLKDLL)	FCLKINLF		25	160	25	160	25	135	MHz
Input Clock Low/High Pulse Width	T_{DLLPW}	≥2□5 MHz	5.0		5.0		5.0		ns
		≥□50 MHz	3.0		3.0		3.0		ns
		≥100 MHz	2.4		2.4		2.4		ns
		≥□150 MHz	2.0		2.0		2.0		ns
		≥□200 MHz	1.8		1.8		1.8		ns
		≥□250 MHz	1.5		1.5		1.5		ns
		≥□300 MHz	1.3		1.3		NA		ns

Period Tolerance: the allowed input clock period change in nanoseconds.



Output Jitter: the difference between an ideal reference clock edge and the actual design.

Phase Offset and Maximum Phase Difference

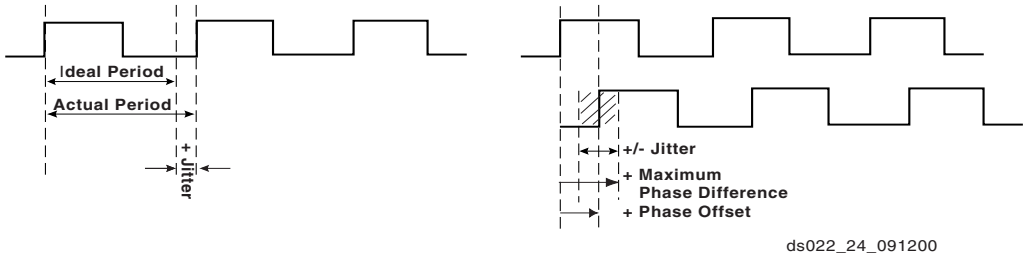


Figure 4: **DLL Timing Waveforms**

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	VCCO	AL31
7	VCCO	A31
7	VCCO	L28
7	VCCO	L31
NA	GND	A2
NA	GND	A3
NA	GND	A7
NA	GND	A9
NA	GND	A14
NA	GND	A18
NA	GND	A23
NA	GND	A25
NA	GND	A29
NA	GND	A30
NA	GND	B1
NA	GND	B2
NA	GND	B30
NA	GND	B31
NA	GND	C1
NA	GND	C31
NA	GND	D16
NA	GND	G1
NA	GND	G31
NA	GND	J1
NA	GND	J31
NA	GND	P1
NA	GND	P31
NA	GND	T4
NA	GND	T28
NA	GND	V1
NA	GND	V31
NA	GND	AC1
NA	GND	AC31
NA	GND	AE1
NA	GND	AE31

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	AH16
NA	GND	AJ1
NA	GND	AJ31
NA	GND	AK1
NA	GND	AK2
NA	GND	AK30
NA	GND	AK31
NA	GND	AL2
NA	GND	AL3
NA	GND	AL7
NA	GND	AL9
NA	GND	AL14
NA	GND	AL18
NA	GND	AL23
NA	GND	AL25
NA	GND	AL29
NA	GND	AL30

Notes:

1. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV400E, XCV600E; otherwise, I/O option only.

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
7	IO	J1
7	IO	J4
7	IO	L2[1]
7	IO_L104N_YY	L3
7	IO_L104P_YY	L4
7	IO_L105N_YY	L5
7	IO_L105P_YY	L1
7	IO_L106N_Y	L6
7	IO_L106P_Y	K2
7	IO_L107N_Y	K4
7	IO_VREF_L107P_Y	K3
7	IO_L108N_YY	K1
7	IO_L108P_YY	K5
7	IO_L109N_YY	J3
7	IO_L109P_YY	J2
7	IO_L110N_YY	J5
7	IO_L110P_YY	H1
7	IO_L111N_YY	H2
7	IO_L111P_YY	H3
7	IO_L112N_Y	G1
7	IO_VREF_L112P_Y	H4
7	IO_L113N_Y	F1
7	IO_L113P_Y	F2
7	IO_L114N_YY	H5
7	IO_L114P_YY	G3
7	IO_L115N_YY	E1
7	IO_VREF_L115P_YY	E2
7	IO_L116N_YY	F3
7	IO_L116P_YY	G5
7	IO_L117N_YY	E3
7	IO_VREF_L117P_YY	D2
7	IO_L118N_YY	F5
7	IO_L118P_YY	C1
2	CCLK	B22
3	DONE	Y19
NA	DXN	Y5

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
NA	DXP	V6
NA	M0	AB2
NA	M1	U5
NA	M2	Y4
NA	PROGRAM	W20
NA	TCK	C4
NA	TDI	B20
2	TDO	A21
NA	TMS	D3
NA	NC	W19
NA	NC	W4
NA	NC	D19
NA	NC	D4
NA	VCCINT	E5
NA	VCCINT	E18
NA	VCCINT	F6
NA	VCCINT	F17
NA	VCCINT	G7
NA	VCCINT	G8
NA	VCCINT	G9
NA	VCCINT	G14
NA	VCCINT	G15
NA	VCCINT	H7
NA	VCCINT	G16
NA	VCCINT	H16
NA	VCCINT	J7
NA	VCCINT	J16
NA	VCCINT	P7
NA	VCCINT	P16
NA	VCCINT	R7
NA	VCCINT	R16
NA	VCCINT	T7
NA	VCCINT	T8
NA	VCCINT	T9
NA	VCCINT	T14

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	2	G24	H22	√	-
53	2	J21	G25	2	-
54	2	G26	J22	1	VREF
55	2	H24	J23	√	-
56	2	J24	K20	√	VREF
57	2	K22	K21	√	D2
58	2	H25	K23	√	-
59	2	L20	J26	2	-
60	2	K25	L22	1	-
61	2	L21	L23	1	-
62	2	M20	L24	1	-
63	2	M23	M22	√	D3
64	2	L26	M21	√	-
65	2	N19	M24	2	-
66	2	M26	N20	1	VREF
67	2	N24	N21	√	-
68	2	N23	N22	√	-
69	3	P21	P23	√	-
70	3	P22	R25	1	VREF
71	3	P19	P20	2	-
72	3	R21	R22	√	-
73	3	R24	R23	√	VREF
74	3	T24	R20	1	-
75	3	T22	U24	1	-
76	3	T23	U25	1	-
77	3	T21	U20	2	-
78	3	U22	V26	√	-
79	3	T20	U23	√	D5
80	3	V24	U21	√	VREF
81	3	V23	W24	√	-
82	3	V22	W26	1	VREF
83	3	Y25	V21	2	-
84	3	V20	AA26	√	-
85	3	Y24	W23	√	VREF

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	3	AA24	Y23	1	-
87	3	AB26	W21	2	-
88	3	Y22	W22	1	VREF
89	3	AA23	AB24	2	-
90	3	W20	AC24	√	-
91	3	AB23	Y21	√	INIT
92	4	AC22	AD26	√	-
93	4	AD23	AA20	1	-
94	4	Y19	AC21	√	-
95	4	AD22	AB20	√	VREF
96	4	AE22	Y18	NA	-
97	4	AF22	AA19	NA	-
98	4	AD21	AB19	√	VREF
99	4	AC20	AA18	√	-
100	4	AC19	AD20	1	-
101	4	AF20	AB18	1	VREF
102	4	AD19	Y17	NA	-
103	4	AE19	AD18	NA	VREF
104	4	AF19	AA17	√	-
105	4	AC17	AB17	1	-
106	4	Y16	AE17	√	-
107	4	AF17	AA16	√	-
108	4	AD17	AB16	NA	-
109	4	AC16	AD16	√	-
110	4	AC15	Y15	√	VREF
111	4	AD15	AA15	√	-
112	4	W14	AB15	1	-
113	4	AF15	Y14	1	VREF
114	4	AD14	AB14	NA	-
115	5	AC14	AF13	NA	IO_LVDS_DLL
116	5	AA13	AF12	1	VREF
117	5	AC13	W13	1	-
118	5	AA12	AD12	√	-
119	5	AC12	AB12	√	VREF

Table 21: **FG676 Differential Pin Pair Summary**
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	5	AD11	Y12	√	-
121	5	AB11	AD10	NA	-
122	5	AC11	AE10	√	-
123	5	AC10	AA11	√	-
124	5	Y11	AD9	1	-
125	5	AB10	AF9	√	-
126	5	AD8	AA10	√	VREF
127	5	AE8	Y10	√	-
128	5	AC9	AF8	1	VREF
129	5	AF7	AB9	1	-
130	5	AA9	AF6	√	-
131	5	AC8	AC7	√	VREF
132	5	AD6	Y9	√	-
133	5	AE5	AA8	√	-
134	5	AC6	AB8	√	VREF
135	5	AD5	AA7	√	-
136	5	AF4	AC5	2	-
137	6	AC3	AA5	√	-
138	6	AB4	AC2	√	-
139	6	AA4	W6	2	-
140	6	Y5	AB3	1	VREF
141	6	V7	AB2	1	-
142	6	Y4	AB1	√	-
143	6	W5	V5	√	VREF
144	6	V6	AA1	√	-
145	6	Y3	W4	2	-
146	6	U7	Y1	1	VREF
147	6	V4	W1	√	-
148	6	U6	W2	√	VREF
149	6	T5	V3	√	-
150	6	U4	U5	√	-
151	6	U3	T7	2	-
152	6	T6	U2	1	-
153	6	T4	U1	1	-

Table 21: **FG676 Differential Pin Pair Summary**
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	6	T3	R7	1	-
155	6	R6	R4	√	VREF
156	6	R5	R3	√	-
157	6	P7	P8	2	-
158	6	P6	R1	1	VREF
159	6	P4	P5	√	-
160	7	N8	N5	√	-
161	7	N3	N6	√	-
162	7	M2	N4	1	VREF
163	7	M7	N7	2	-
164	7	M3	M6	√	-
165	7	M5	M4	√	VREF
166	7	L7	L3	1	-
167	7	K2	L6	1	-
168	7	K1	L4	1	-
169	7	L5	K3	2	-
170	7	J3	K5	√	-
171	7	J4	K4	√	-
172	7	K6	H3	√	VREF
173	7	G3	K7	√	-
174	7	H1	J5	1	VREF
175	7	J6	G2	2	-
176	7	F1	J7	√	-
177	7	G4	H4	√	VREF
178	7	H5	F3	1	-
179	7	H6	E2	2	-
180	7	F4	G5	1	VREF
181	7	G6	H7	2	-
182	7	E4	E3	√	-

Notes:
1. AO in the XCV600E.
2. AO in the XCV400E.

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
4	IO_L147N_YY	AW7
4	IO_L148P_Y	AY7
4	IO_L148N_Y	BB8
4	IO_L149P_Y	BA9
4	IO_L149N_Y	AV8
4	IO_L150P_YY	AW8
4	IO_L150N_YY	BA10
4	IO_VREF_L151P_YY	BB10
4	IO_L151N_YY	AY8
4	IO_L152P_Y	AV9
4	IO_L152N_Y	BA11
4	IO_VREF_L153P_Y	BB11[2]
4	IO_L153N_Y	AW9
4	IO_L154P_YY	AY9
4	IO_L154N_YY	BA12
4	IO_VREF_L155P_YY	BB12
4	IO_L155N_YY	AV10
4	IO_L156P_Y	BA13
4	IO_L156N_Y	AW10
4	IO_L157P_Y	BB13
4	IO_L157N_Y	AY10
4	IO_VREF_L158P_YY	AV11
4	IO_L158N_YY	BA14
4	IO_L159P_YY	AW11
4	IO_L159N_YY	BB14
4	IO_L160P_Y	AV12
4	IO_L160N_Y	BA15
4	IO_L161P_Y	AW12
4	IO_L161N_Y	AY15
4	IO_L162P_Y	AW13
4	IO_L162N_Y	BB15
4	IO_L163P_Y	AV14
4	IO_L163N_Y	BA16
4	IO_L164P_YY	AW14
4	IO_L164N_YY	AY16
4	IO_VREF_L165P_YY	BB16
4	IO_L165N_YY	AV15
4	IO_L166P_Y	AY17
4	IO_L166N_Y	AW15
4	IO_L167P_Y	BB17
4	IO_L167N_Y	AU16
4	IO_L168P_YY	AV16
4	IO_L168N_YY	AY18
4	IO_VREF_L169P_YY	AW16
4	IO_L169N_YY	BA18
4	IO_L170P_Y	BB19
4	IO_L170N_Y	AW17
4	IO_L171P_Y	AY19
4	IO_L171N_Y	AV18
4	IO_L172P_YY	AW18
4	IO_L172N_YY	BB20
4	IO_VREF_L173P_YY	AY20
4	IO_L173N_YY	AV19
4	IO_L174P_Y	BB21
4	IO_L174N_Y	AW19
4	IO_VREF_L175P_Y	AY21[1]
4	IO_L175N_Y	AV20
4	IO_LVDS_DLL_L176P	AW20
5	GCK1	AY22
5	IO	AV24
5	IO	AV34
5	IO	AW27
5	IO	AW36
5	IO	AY23
5	IO	AY31
5	IO	AY33
5	IO	BA26
5	IO	BA29
5	IO	BA33
5	IO	BB25
5	IO_LVDS_DLL_L176N	AW21
5	IO_L177P_Y	BB22
5	IO_VREF_L177N_Y	AW22[1]

Table 25: **FG860 Differential Pin Pair Summary**
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	D11	B15	√	VREF
53	1	C14	E11	2	-
54	1	B14	C10	2	-
55	1	E10	A13	√	VREF
56	1	C9	C13	√	-
57	1	A12	D9	1	VREF
58	1	C12	E9	1	-
59	1	D8	B12	√	VREF
60	1	E8	A11	√	-
61	1	A10	C7	5	-
62	1	B10	C6	5	-
63	1	B9	A9	√	VREF
64	1	E7	A8	√	-
65	1	C5	B8	5	-
66	1	A6	A7	1	VREF
67	1	D6	B7	1	-
68	1	C4	A5	2	-
69	1	E6	B6	√	CS
70	2	F5	D2	√	DIN, D0
71	2	E4	E2	3	-
72	2	D3	F2	1	-
73	2	E1	F4	2	VREF
74	2	G2	E3	4	-
75	2	F1	G5	2	-
76	2	G1	F3	1	VREF
77	2	G4	H1	√	-
78	2	J2	G3	2	-
79	2	H5	K2	1	-
80	2	H4	K1	√	VREF
81	2	L2	L3	√	-
82	2	L1	J5	5	VREF
83	2	J4	M3	2	-
84	2	J3	M1	√	VREF
85	2	N2	K4	√	-

Table 25: **FG860 Differential Pin Pair Summary**
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	N3	K3	2	-
87	2	L5	P2	√	D1
88	2	P3	L4	√	D2
89	2	P1	R2	3	-
90	2	M5	R3	1	-
91	2	M4	R1	2	-
92	2	N4	T2	4	-
93	2	P5	T3	2	-
94	2	P4	T1	1	VREF
95	2	U2	R4	√	-
96	2	U3	T5	2	-
97	2	T4	V2	1	-
98	2	U5	V3	√	D3
99	2	V1	V5	√	-
100	2	W2	V4	5	-
101	2	W5	W1	2	-
102	2	Y2	W4	√	VREF
103	2	Y1	Y5	√	-
104	2	AA1	Y4	2	VREF
105	2	AA4	AA2	√	-
106	3	AB3	AC4	2	VREF
107	3	AB1	AC5	√	-
108	3	AD4	AC3	√	VREF
109	3	AC1	AD5	2	-
110	3	AE4	AD3	5	-
111	3	AE5	AD2	√	-
112	3	AE1	AF5	√	VREF
113	3	AE2	AG4	1	-
114	3	AG5	AF1	2	-
115	3	AH4	AF2	√	-
116	3	AF3	AJ4	1	VREF
117	3	AG1	AJ5	2	-
118	3	AG2	AK4	4	-
119	3	AG3	AL4	2	-

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
5	IO_L182N	AF13
5	IO_L183P	AH14
5	IO_L183N	AJ14
5	IO_L184P_YY	AE14
5	IO_VREF_L184N_YY	AG13
5	IO_L185P_YY	AK13
5	IO_L185N_YY	AD13
5	IO_L186P	AE13
5	IO_L186N	AF12
5	IO_L187P	AC13
5	IO_L187N	AA13
5	IO_L188P_YY	AA12
5	IO_VREF_L188N_YY	AJ12[1]
5	IO_L189P_YY	AB12
5	IO_L189N_YY	AE11
5	IO_L190P	AK12[4]
5	IO_L190N	Y13[4]
5	IO_L191P	AG11
5	IO_L191N	AF11
5	IO_L192P	AH11
5	IO_L192N	AJ11
5	IO_L193P_YY	AE12[4]
5	IO_L193N_YY	AG10[4]
5	IO_L194P_YY	AD12
5	IO_L194N_YY	AK11
5	IO_L195P_YY	AJ10
5	IO_VREF_L195N_YY	AC12
5	IO_L196P_YY	AK10
5	IO_L196N_YY	AD11
5	IO_L197P_YY	AJ9
5	IO_L197N_YY	AE9
5	IO_L198P_YY	AH10
5	IO_VREF_L198N_YY	AF9
5	IO_L199P_YY	AH9
5	IO_L199N_YY	AK9
5	IO_L200P	AF8
5	IO_L200N	AB11

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
5	IO_L201P	AC11
5	IO_L201N	AG8
5	IO_L202P_YY	AK8
5	IO_VREF_L202N_YY	AF7
5	IO_L203P_YY	AG7
5	IO_L203N_YY	AK7
5	IO_L204P	AJ7
5	IO_L204N	AD10
5	IO_L205P	AH6
5	IO_L205N	AC10
5	IO_L206P_YY	AD9
5	IO_VREF_L206N_YY	AG6
5	IO_L207P_YY	AB10
5	IO_L207N_YY	AJ5
5	IO_L208P	AD8[4]
5	IO_L208N	AK5[4]
5	IO_L209P	AC9
5	IO_VREF_L209N	AJ4[1]
5	IO_L210P	AG5
5	IO_L210N	AK4
5	IO_L211P_YY	AH5[3]
5	IO_L211N_YY	AG3[4]
6	IO	T2[4]
6	IO	T10[4]
6	IO	U1
6	IO	U4[5]
6	IO	U6[4]
6	IO	U7[4]
6	IO	V1[4]
6	IO	V5[5]
6	IO	V8
6	IO	Y10[4]
6	IO	AA4[4]
6	IO	AB5[5]
6	IO	AB7[4]
6	IO	AC3[5]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	AG27
NA	GND	D27
NA	GND	AF26
NA	GND	E26
NA	GND	F25
NA	GND	AE25
NA	GND	G24
NA	GND	AJ23
NA	GND	AD24
NA	GND	H23
NA	GND	B23
NA	GND	AC23
NA	GND	AB22
NA	GND	V22
NA	GND	N22
NA	GND	AH18
NA	GND	AB18
NA	GND	J18
NA	GND	C18
NA	GND	U17
NA	GND	T17
NA	GND	R17
NA	GND	P17
NA	GND	U16
NA	GND	T16
NA	GND	R16
NA	GND	P16
NA	GND	U15
NA	GND	T15
NA	GND	R15
NA	GND	P15
NA	GND	U14
NA	GND	T14
NA	GND	R14
NA	GND	P14
NA	GND	AH13
NA	GND	AB13

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	J13
NA	GND	C13
NA	GND	V9
NA	GND	N9
NA	GND	J9
NA	GND	AJ8
NA	GND	AC8
NA	GND	H8
NA	GND	AD7
NA	GND	B8
NA	GND	AE6
NA	GND	G7
NA	GND	F6
NA	GND	AF5
NA	GND	E5
NA	GND	AG4
NA	GND	D4
NA	GND	V3
NA	GND	N3
NA	GND	C3
NA	GND	AK2
NA	GND	AH3
NA	GND	AC2
NA	GND	H2
NA	GND	B2
NA	GND	A2
NA	GND	AK1
NA	GND	AJ2
NA	GND	AJ1
NA	GND	A1
NA	GND	B1

Notes:

1. V_{REF} or I/O option only in the XCV1000E and XCV1600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV1600E; otherwise, I/O option only.
3. I/O option only in the XCV600E.
4. No Connect in the XCV600E.
5. No Connect in the XCV600E, 1000E.

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
256	7	N6	M6	1	-
257	7	N1	N5	4	-
258	7	M5	M4	√	-
259	7	M1	M2	1	VREF
260	7	L2	L4	4	-
261	7	L5	M7	3	-
262	7	M8	L1	4	-
263	7	M9	K2	1	-
264	7	M10	L3	NA	-
265	7	K1	K5	√	-
266	7	K3	L6	√	VREF
267	7	K4	L7	4	-
268	7	J5	L8	4	-
269	7	H4	K6	4	VREF
270	7	K7	H1	4	-
271	7	J2	J7	2	-
272	7	G2	H5	√	-
273	7	G5	L9	√	VREF
274	7	K8	F3	1	-
275	7	E1	G3	4	-
276	7	E2	H6	√	-
277	7	K9	E4	1	VREF
278	7	F4	J8	4	-
279	7	H7	D1	3	-
280	7	C2	G6	4	VREF
281	7	F5	D2	1	-
282	7	K10	D3	4	-

Notes:
1. AO in the XCV600E, 1000E.
2. AO in the XCV1000E.
3. AO in the XCV1600E.
4. AO in the XCV1000E, XCV1600E.

FG1156 Fine-Pitch Ball Grid Array Package

XCV1000E, XCV1600E, XCV2000E, XCV2600E, and XCV3200E devices in the FG1156 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either V_{REF} or general I/O, unless indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 28, see Table 29 for Differential Pair information.

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	GCK3	E17
0	IO	B4
0	IO	B9
0	IO	B10
0	IO	D9[3]
0	IO	D16
0	IO	E7[3]
0	IO	E11[3]
0	IO	E13[3]
0	IO	E16[3]
0	IO	F17[3]
0	IO	J12[3]
0	IO	J13[3]
0	IO	J14[3]
0	IO	K11[3]
0	IO_L0N_Y	F7
0	IO_L0P_Y	H9
0	IO_L1N_Y	C5
0	IO_L1P_Y	J10
0	IO_VREF_L2N_Y	E6
0	IO_L2P_Y	D6
0	IO_L3N_Y	A4
0	IO_L3P_Y	G8
0	IO_L4N_YY	C6
0	IO_L4P_YY	J11
0	IO_VREF_L5N_YY	G9
0	IO_L5P_YY	F8
0	IO_L6N_YY	A5[4]

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
4	IO_L212N_YY	AP18
4	IO_L213P_Y	AF18
4	IO_L213N_Y	AP17
4	IO_VREF_L214P_Y	AJ18[1]
4	IO_L214N_Y	AL18
4	IO_LVDS_DLL_L215P	AM18
5	GCK1	AL19
5	IO	AF17[3]
5	IO	AG12[3]
5	IO	AH12
5	IO	AJ10[3]
5	IO	AJ11[3]
5	IO	AK7[3]
5	IO	AK13[3]
5	IO	AL13[3]
5	IO	AM4[3]
5	IO	AN9
5	IO	AN10[3]
5	IO	AN16
5	IO	AN17[3]
5	IO_LVDS_DLL_L215N	AL17
5	IO_L216P_Y	AH17
5	IO_VREF_L216N_Y	AM17[1]
5	IO_L217P_Y	AJ17
5	IO_L217N_Y	AG17
5	IO_L218P_YY	AP16
5	IO_VREF_L218N_YY	AL16
5	IO_L219P_YY	AJ16
5	IO_L219N_YY	AM16
5	IO_L220P	AK16[5]
5	IO_L220N	AP15[4]
5	IO_L221P_Y	AL15
5	IO_L221N_Y	AH16

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
5	IO_L222P_Y	AN15
5	IO_L222N_Y	AF16
5	IO_L223P_Y	AP14[5]
5	IO_L223N_Y	AE16[4]
5	IO_L224P_YY	AK15
5	IO_VREF_L224N_YY	AJ15
5	IO_L225P_YY	AH15
5	IO_L225N_YY	AN14
5	IO_L226P	AK14[5]
5	IO_L226N	AG15[4]
5	IO_L227P_Y	AM13
5	IO_L227N_Y	AF15
5	IO_L228P_Y	AG14
5	IO_L228N_Y	AP13
5	IO_L229P_YY	AE14[5]
5	IO_L229N_YY	AE15[4]
5	IO_L230P_YY	AN13
5	IO_VREF_L230N_YY	AG13
5	IO_L231P_YY	AH14
5	IO_L231N_YY	AP12
5	IO_L232P_Y	AJ14
5	IO_L232N_Y	AL14
5	IO_L233P_Y	AF13
5	IO_L233N_Y	AN12
5	IO_L234P_Y	AF14
5	IO_L234N_Y	AP11
5	IO_L235P_Y	AN11
5	IO_L235N_Y	AH13
5	IO_L236P_YY	AM12
5	IO_L236N_YY	AL12
5	IO_L237P_YY	AJ13
5	IO_VREF_L237N_YY	AP10
5	IO_L238P_Y	AK12
5	IO_L238N_Y	AM10

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
6	IO_VREF_L265N_Y	AJ3
6	IO_L265P_Y	AG5
6	IO_L266N_YY	AD9[4]
6	IO_L266P_YY	AJ2[5]
6	IO_L267N_YY	AC10
6	IO_L267P_YY	AH2
6	IO_L268N_Y	AH3
6	IO_L268P_Y	AF5
6	IO_L269N_Y	AE8[4]
6	IO_L269P_Y	AG3[5]
6	IO_L270N_Y	AE7
6	IO_L270P_Y	AG2
6	IO_VREF_L271N_YY	AF6
6	IO_L271P_YY	AG1
6	IO_L272N_YY	AC9[4]
6	IO_L272P_YY	AG4[5]
6	IO_L273N_YY	AE6
6	IO_L273P_YY	AF3
6	IO_VREF_L274N_Y	AF1[2]
6	IO_L274P_Y	AF4
6	IO_L275N	AB10[4]
6	IO_L275P	AF2[5]
6	IO_L276N_Y	AC8
6	IO_L276P_Y	AE1
6	IO_VREF_L277N_YY	AD5
6	IO_L277P_YY	AE3
6	IO_L278N_YY	AC7
6	IO_L278P_YY	AD1
6	IO_L279N_Y	AD6
6	IO_L279P_Y	AD2
6	IO_VREF_L280N_YY	AB8
6	IO_L280P_YY	AC1
6	IO_L281N_YY	AC5
6	IO_L281P_YY	AC2

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
6	IO_L282N_Y	AA9
6	IO_L282P_Y	AC3
6	IO_L283N_Y	AC4
6	IO_L283P_Y	AD4
6	IO_L284N_Y	AA8
6	IO_L284P_Y	AB6
6	IO_L285N	AB1
6	IO_L285P	Y10
6	IO_L286N_Y	AB2
6	IO_L286P_Y	AA7
6	IO_VREF_L287N_Y	AA4
6	IO_L287P_Y	AA1
6	IO_L288N_YY	Y9[4]
6	IO_L288P_YY	AB4[5]
6	IO_L289N_YY	AA2
6	IO_L289P_YY	Y8
6	IO_L290N_Y	AA6
6	IO_L290P_Y	AA5
6	IO_L291N_Y	AB3[4]
6	IO_L291P_Y	Y7[5]
6	IO_L292N_Y	Y1
6	IO_L292P_Y	W10
6	IO_VREF_L293N_YY	Y5
6	IO_L293P_YY	Y2
6	IO_L294N_YY	W9[4]
6	IO_L294P_YY	W2[5]
6	IO_L295N_YY	W7
6	IO_L295P_YY	Y4
6	IO_L296N_Y	W1
6	IO_L296P_Y	Y6
6	IO_L297N_Y	W6[4]
6	IO_L297P_Y	W3[5]
6	IO_L298N_Y	V9
6	IO_L298P_Y	W4

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
111	2	M31	R26	2600 1600	-
112	2	N30	P28	3200 1600 1000	-
113	2	N29	N33	2600 2000 1000	VREF
114	2	T25	N34	3200 2600 2000 1600	-
115	2	P34	R27	3200 2600 2000 1600 1000	-
116	2	P29	P31	3200 2600 1600 1000	-
117	2	P33	T26	3200 2600 2000	-
118	2	R34	R28	2600 2000 1000	-
119	2	N31	N32	2000 1600 1000	D3
120	2	P30	R33	2000 1600	-
121	2	R29	T34	3200 2600 2000 1600 1000	-
122	2	R30	T30	1000	-
123	2	T28	R31	3200 1600	-
124	2	T29	U27	3200 2600 1600 1000	-
125	2	T31	T33	2000 1600 1000	VREF
126	2	U28	T32	2000 1600 1000	-
127	2	U29	U33	3200 2600 1600 1000	VREF
128	2	V33	U31	3200 2600 2000 1600 1000	-
129	3	V26	V30	3200 2600 1600 1000	VREF
130	3	W34	V28	2000 1600 1000	-
131	3	W32	W30	2000 1600 1000	VREF

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
132	3	V29	Y34	3200 2600 1600 1000	-
133	3	W29	Y33	3200 1600	-
134	3	W26	W28	1000	-
135	3	Y31	Y30	3200 2600 2000 1600 1000	-
136	3	AA34	W31	2000 1600	-
137	3	AA33	Y29	2000 1600 1000	VREF
138	3	W25	AB34	2600 2000 1000	-
139	3	Y28	AB33	3200 2600 2000	-
140	3	AA30	Y26	3200 2600 1600 1000	-
141	3	Y27	AA31	3200 2600 2000 1600 1000	-
142	3	AA27	AA29	3200 2600 2000 1600	-
143	3	AB32	AB29	2600 2000 1000	VREF
144	3	AA28	AC34	3200 1600 1000	-
145	3	Y25	AD34	2600 1600	-
146	3	AB30	AC33	3200 2600 1600 1000	-
147	3	AA26	AC32	2000 1000	-
148	3	AD33	AB28	3200 2600 2000	-
149	3	AE34	AB27	3200 2600 2000 1600 1000	D5
150	3	AE33	AC30	2000 1600 1000	VREF
151	3	AA25	AE32	3200 1600 1000	-
152	3	AE31	AD29	3200 2600 2000 1600 1000	-